

What is claimed is:

Sub B1
1. A method of fabricating a semiconductor device comprising:

5 a step (a) of attaching a plurality of semiconductor chips to a tape;

a step (b) of cutting the tape; and

a step (c) of providing a plurality of external terminals on a substrate cut from the tape in the step (b),

10 wherein the steps (a) and (b) are carried out in a reel-to-reel transport system.

2. The method of fabricating a semiconductor device as defined in claim 1, further comprising:

15 a step of adhering a reinforcing member to the tape in positions corresponding to each of the semiconductor chips, before the step (b).

3. The method of fabricating a semiconductor device as defined in claim 1,

20 wherein the tape is cut into regions each including one of the semiconductor chips in the step (b).

4. The method of fabricating a semiconductor device as defined in claim 2,

25 wherein the tape is cut into regions each including one of the semiconductor chips in the step (b).

5. The method of fabricating a semiconductor device as defined in claim 1,

wherein the tape is cut into regions each including two or more of the semiconductor chips in the step (b).

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6. The method of fabricating a semiconductor device as defined in claim 2,

wherein the tape is cut into regions each including two or more of the semiconductor chips in the step (b).

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7. The method of fabricating a semiconductor device as defined in claim 5,

wherein the substrate cut from the tape is further cut into the semiconductor chips after the step (c).

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8. The method of fabricating a semiconductor device as defined in claim 6,

wherein the substrate cut from the tape is further cut into the semiconductor chips after the step (c).

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9. The method of fabricating a semiconductor device as defined in claim 1,

wherein a plurality of device holes are formed in the tape, and leads are formed above the tape, whose end portions project into the respective device holes; and

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wherein each of the semiconductor chips is disposed within a respective of the device holes, and the electrodes of the semiconductor chips and the leads are bonded in the step

(a).

10. The method of fabricating a semiconductor device as defined in claim 1,

5 wherein each of the semiconductor chips is bonded to the tape in a face-down configuration in the step (a).

11. The method of fabricating a semiconductor device as defined in claim 10,

10 wherein by means of an anisotropic conductive material, the electrodes of the semiconductor chips and leads formed above the tape are electrically connected in the step (a).

12. The method of fabricating a semiconductor device as defined in claim 1,

15 wherein each of the semiconductor chips is bonded to the tape in a face-up configuration in the step (a).

13. The method of fabricating a semiconductor device as defined in claim 12,

20 wherein the electrodes of the semiconductor chips and leads formed above the tape are electrically connected by means of wires in the step (a).

25 14. The method of fabricating a semiconductor device as defined in claim 1, further comprising:

a step of adhering a heat radiating member to each of the semiconductor chips.

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15. The method of fabricating a semiconductor device as defined in claim 2, further comprising:

5 a step of adhering a heat radiating member to each of the semiconductor chips.

16. The method of fabricating a semiconductor device as defined in claim 14,

10 wherein the step of adhering the heat radiating member is carried out before the step (b), with a reel-to-reel transport system.

17. The method of fabricating a semiconductor device as defined in claim 15,

15 wherein the step of adhering the heat radiating member is carried out before the step (b), with a reel-to-reel transport system.

18. A semiconductor device fabricated by the method as defined in claim 1.

19. A circuit board having mounted the semiconductor device as defined in claim 18.

20. An electronic apparatus including the semiconductor device as defined in claim 18.